

10 9 8 7 6 5 4 3 2 1

注記 NOTES

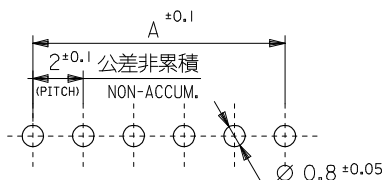
1. 嵌合相手 : 51065 シリーズ
MATE WITH : 51065 SERIES
2. 材質 MATERIAL
ウエハー : ポリアミド、UL94V-0
WAFER : PA, UL94V-0
ピン : 黄銅、金メッキ
PIN : BRASS, GOLD (Au) PLATING

3. キングは下記表の位置及び形状に付加のこと。2極はキング無し。
KINK TO BE APPLIED AS FOLLOWS,
2 CIRCUIT HAS NO KINK.

回路番号		Circuit No.								
極数 Ckt	ckt no.	1	2	3	4	5	N-2	N-1	N	
6 極以上	MORE THAN 6 Ckt	—	①	②	—	—	②	①	—	
5 極	5 Ckt	①	②	—	②	①				
4 極	4 Ckt	①	②	②	①					
3 極	3 Ckt	①	②	①						

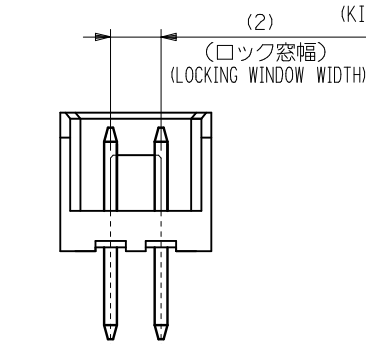
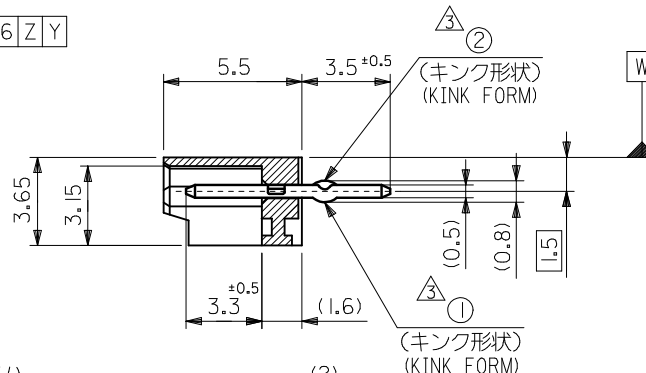
4. 本製品は、53253-**70 の金メッキ品です。
THIS PRODUCT IS AU PLATING OF 53253-**70.
5. 梱包仕様 PACKAGING
502603-**70 トレー TRAY

32	31.1	28	502603-1570	15
30	29.1	26	4 -1470	14
28	27.1	24	-1370	13
26	25.1	22	-1270	12
24	23.1	20	-1170	11
22	21.1	18	-1070	10
20	19.1	16	-0970	9
18	17.1	14	-0870	8
16	15.1	12	-0770	7
14	13.1	10	-0670	6
12	11.1	8	-0570	5
10	9.1	6	7 -0470	4
8	7.1	4	-0370	3
6	5.1	2	502603-0270	2
C	B	A	MATERIAL NO.	極数
MODEL NO.		502603-**70		

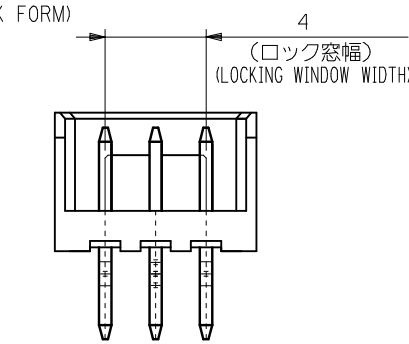


基板取付穴寸法 (参考) (t=1.6)

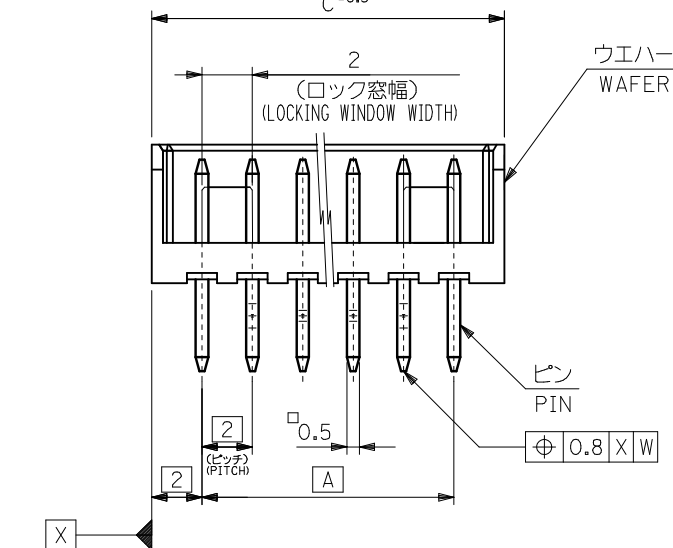
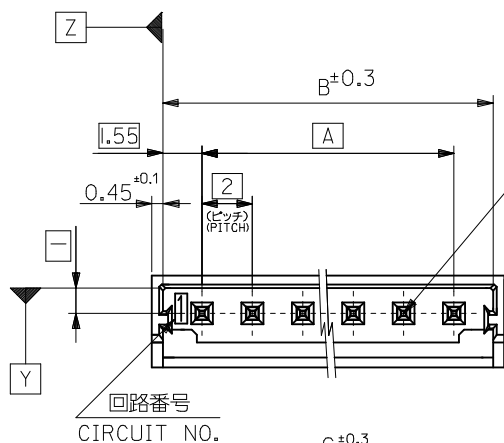
RECOMMENDED P.C. BOARD HOLE DIM. (REFERENCE)



2 極の場合
IN CASE OF 2 CIRCUIT WAFER



3 極の場合
IN CASE OF 3 CIRCUIT WAFER



REVISED EC NO: J2017-0462 DRAWNKUSATO CHKD-AIDA APPR:TKANEKO	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)			DIMENSION STYLE MM ONLY		SCALE 5:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		0.25 UNDER UNDER ±0.03	DRAWN BY DATE	TITLE NEW 2.0 WIRE TO BOARD CONN. WAFER ASSY (ST.) -LEAD FREE-							
		0.25 OVER 0.5 UNDER ±0.05	YMAEDA 2007/03/30								
		0.5 OVER 1.0 UNDER ±0.1	CHECKED BY DATE	MATERIAL NO.							
		1.0 OVER 10 UNDER ±0.2	KTOYOTA 2007/03/30								
		10 OVER 30 UNDER ±0.25	APPROVED BY DATE	DOCUMENT NO.							
		30 OVER ±0.3	NUKITA 2007/03/30								
		ANGULAR ±3 °			MATERIAL NO.		SHEET NO.				
					SEE CHART						
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

10 9 8 7 6 5 4 3 2 1

注記 NOTES

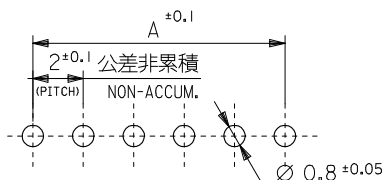
1. 嵌合相手 : 51065 シリーズ
MATE WITH : 51065 SERIES
2. 材質 MATERIAL
ウエハー : ポリアミド、UL94V-0
WAFER : PA, UL94V-0
ピン : 黄銅、金メッキ
PIN : BRASS, GOLD (Au) PLATING

3. キングは下記表の位置及び形状に付加のこと。2極はキング無し。
KINK TO BE APPLIED AS FOLLOWS,
2 CIRCUIT HAS NO KINK.

回路番号		Circuit No.								
極数 Ckt	ckt no.	1	2	3	4	5	N-2	N-1	N	
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5 極	5 Ckt	①	②	—	②	①				
4 極	4 Ckt	①	②	②	①					
3 極	3 Ckt	①	②	①						

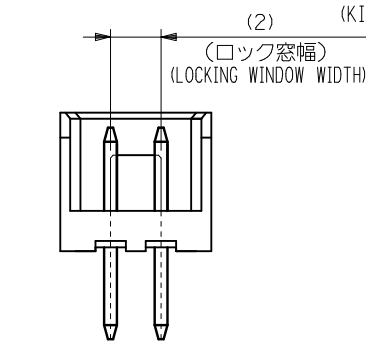
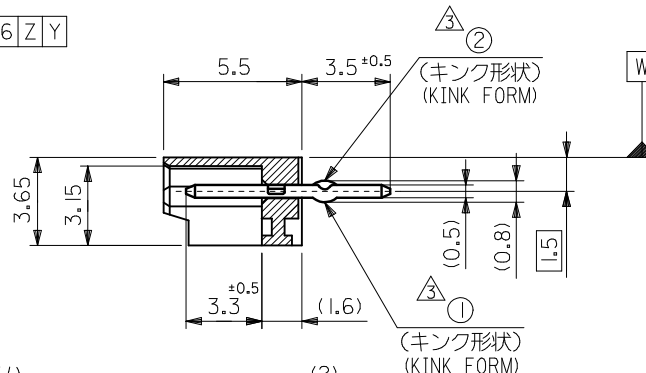
4. 本製品は、53253-**70 の金メッキ品です。
THIS PRODUCT IS AU PLATING OF 53253-**70.
5. 梱包仕様 PACKAGING
502603-**70 トレー TRAY

32	31.1	28	502603-1570	15
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C	B	A	MATERIAL NO.	極数
MODEL NO.		502603-**70		

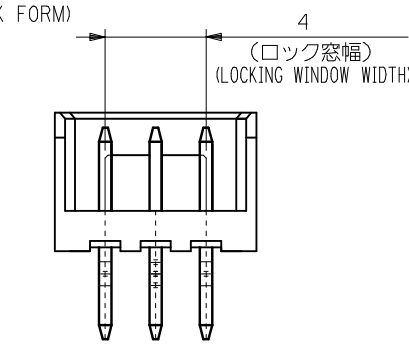


基板取付穴寸法 (参考) (t=1.6)

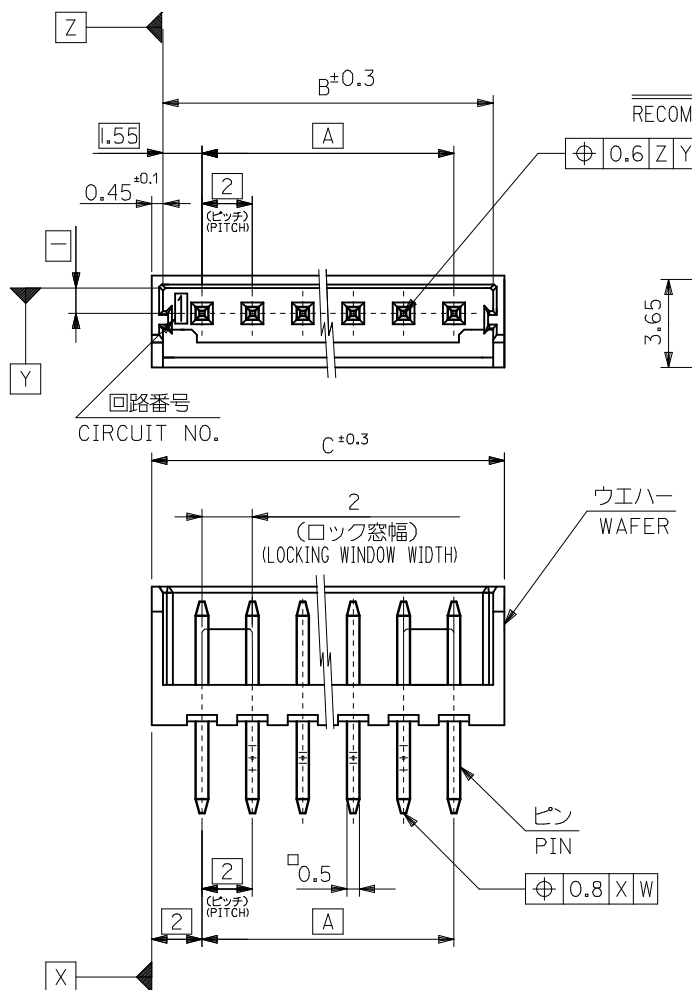
RECOMMENDED P.C. BOARD HOLE DIM. (REFERENCE)



2 極の場合
IN CASE OF 2 CIRCUIT WAFER



3 極の場合
IN CASE OF 3 CIRCUIT WAFER



REVISED EC NO: J2047-0462 DRAWNKUSATO CHFKD-AIDA APPR:TKANEKO	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)			DIMENSION STYLE MM ONLY		SCALE 5:1	DESIGN UNITS METRIC	MODULE NO. 502603-001 THIRD ANGLE PROJECTION	
		0.25 UNDER UNDER ±0.03	DRAWN BY DATE	TITLE NEW 2.0 WIRE TO BOARD CONN. WAFER ASSY (ST.) -LEAD FREE- molex SD-502603-001						
		0.25 OVER 0.5 UNDER ±0.05	YMAEDA 2007/03/30							
		0.5 OVER 1.0 UNDER ±0.1	CHECKED BY DATE							
		1.0 OVER 10 UNDER ±0.2	KTOYOTA 2007/03/30							
		10 OVER 30 UNDER ±0.25	APPROVED BY DATE							
		30 OVER ±0.3	NUKITA 2007/03/30	DOCUMENT NO.			SHEET NO.			
		ANGULAR ±3 °			SEE CHART		SD-502603-001			1 OF 1
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				